

Temperature-centric Reliability Analysis and Optimization Under Process Variation

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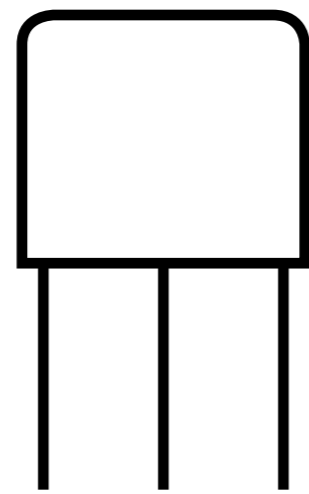
Embedded Systems Laboratory
Linköping University, Sweden

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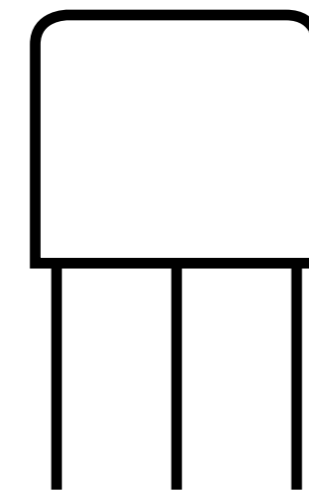
Topics

- * Uncertainty quantification
- * Temperature analysis
- * Reliability analysis
- * Design-space exploration

Process Variation

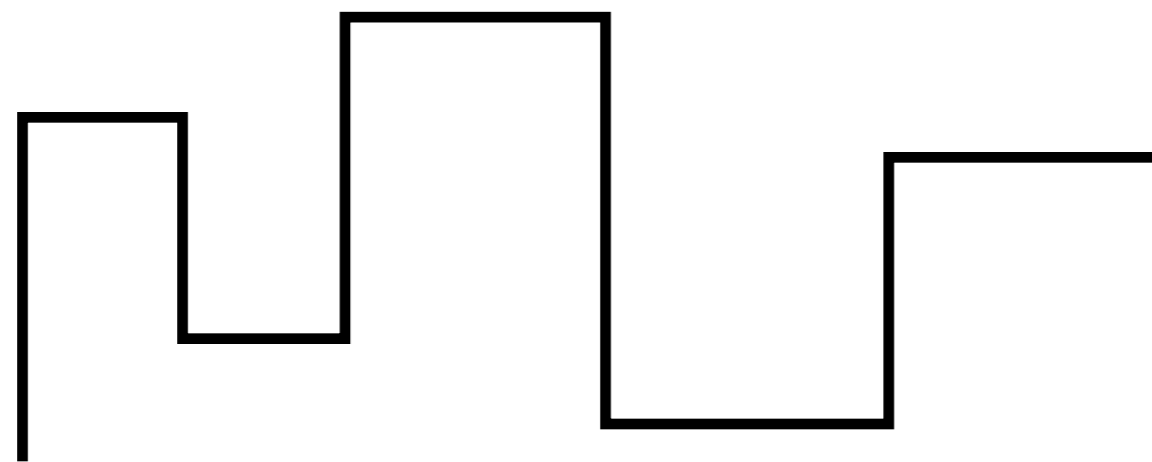


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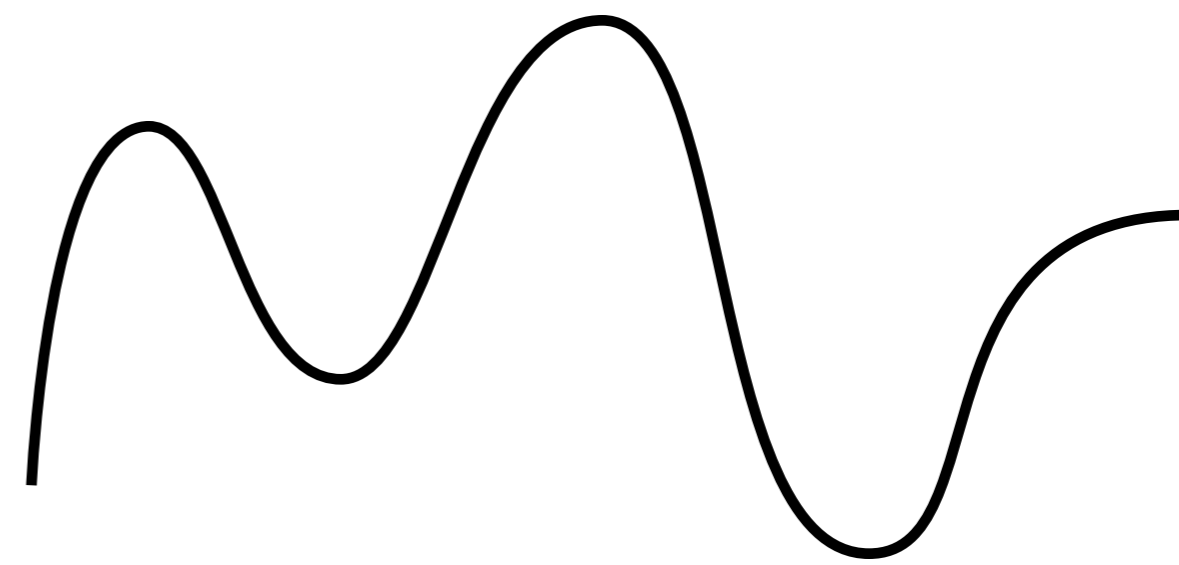


Temperature Analysis

* Transient



Power



Temperature

Temperature Analysis

* Static steady-state

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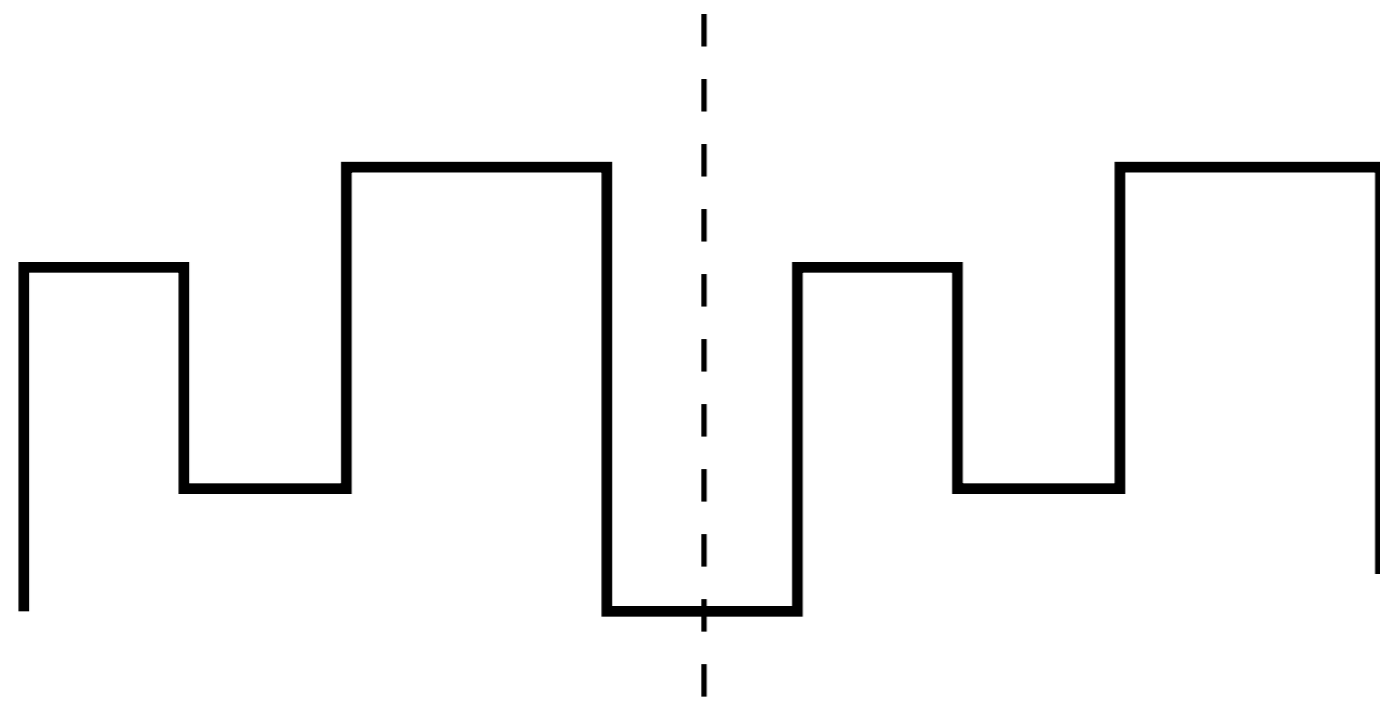
Power

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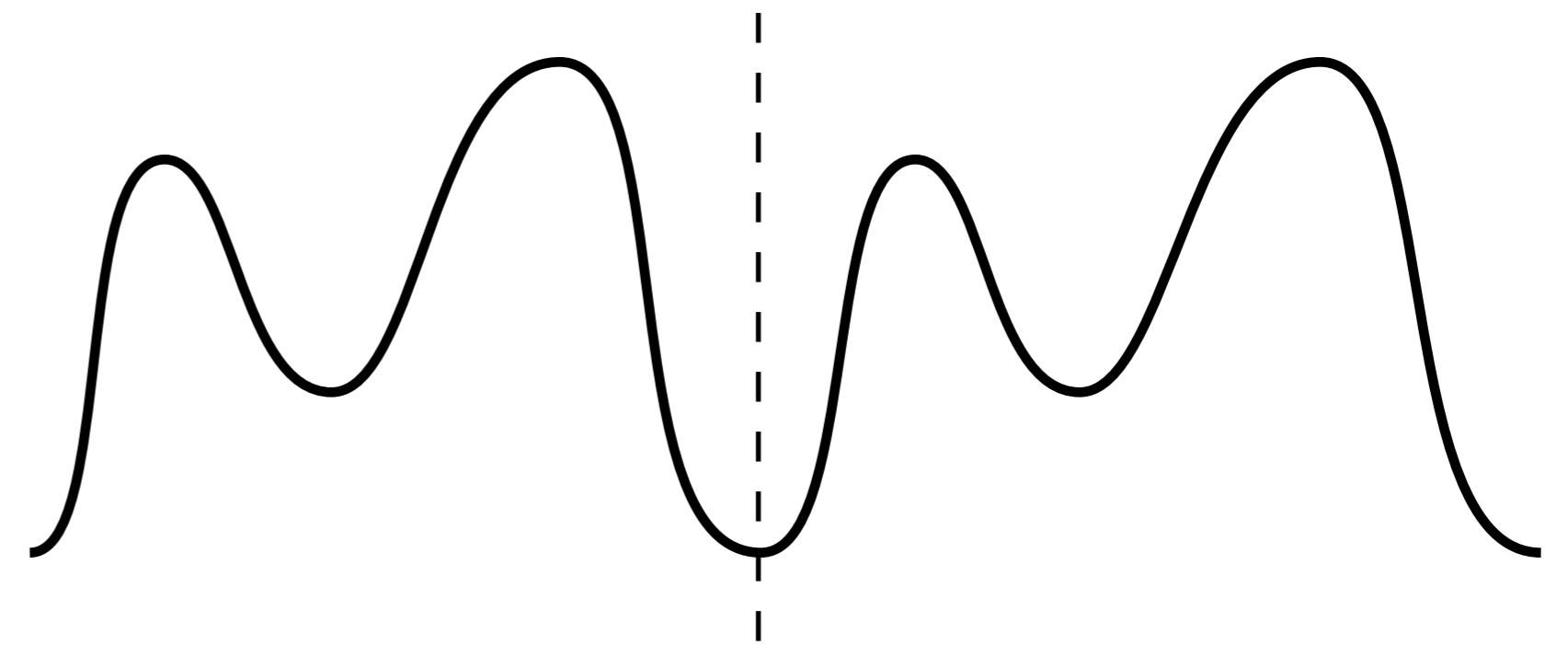
Temperature

Temperature Analysis

* Dynamic steady-state



Power



Temperature

Temperature Process Variation *Analysis Under*

- * Transient
- * Static steady-state
- * Dynamic steady-state

Prior Work

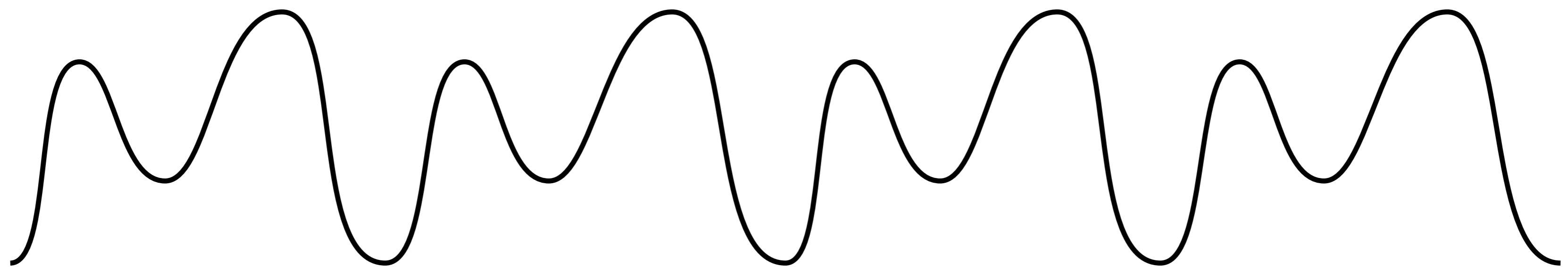
- * Transient [1]
- * Static steady-state [2, ...]
- * Dynamic steady-state

[1] Ukhov *et al.*, TCAD, 2014.

[2] ...

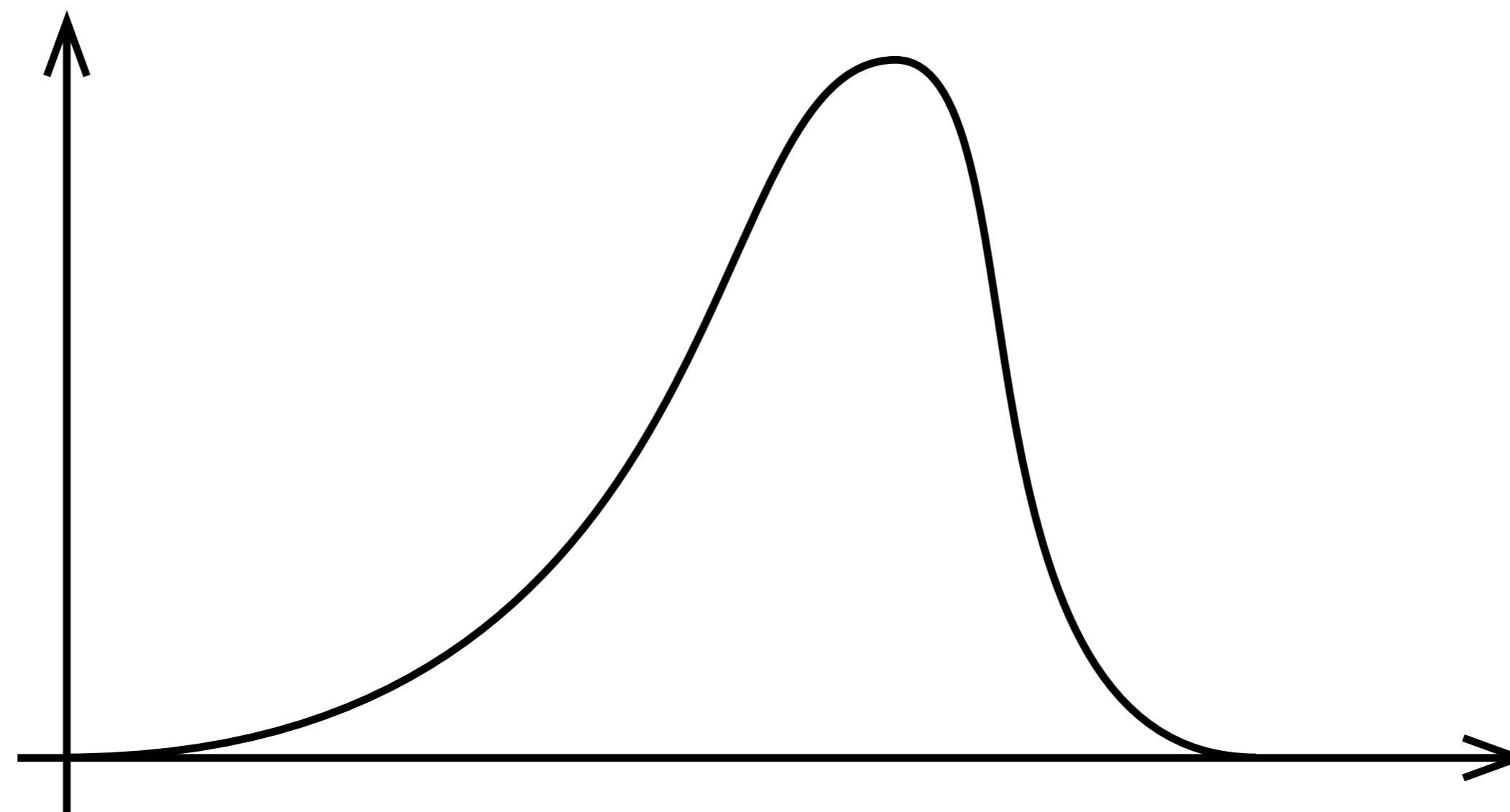
Failure Mechanisms

- * ...
- * Thermal cycling
- * ...



Reliability Analysis

Probability
density



Lifetime

Reliability *Analysis Under* Process Variation

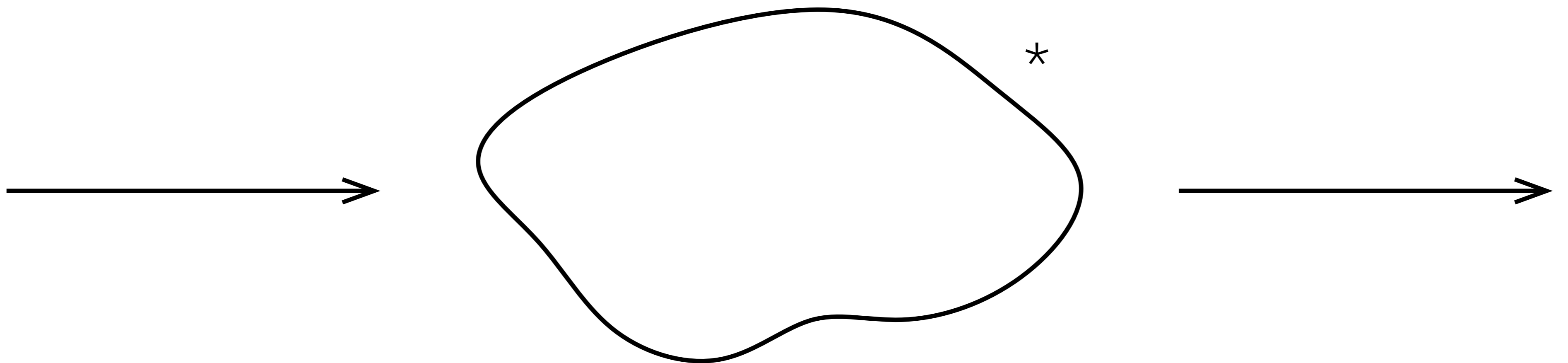
- * ...
- * Thermal cycling
- * ...

Prior Work

Goals

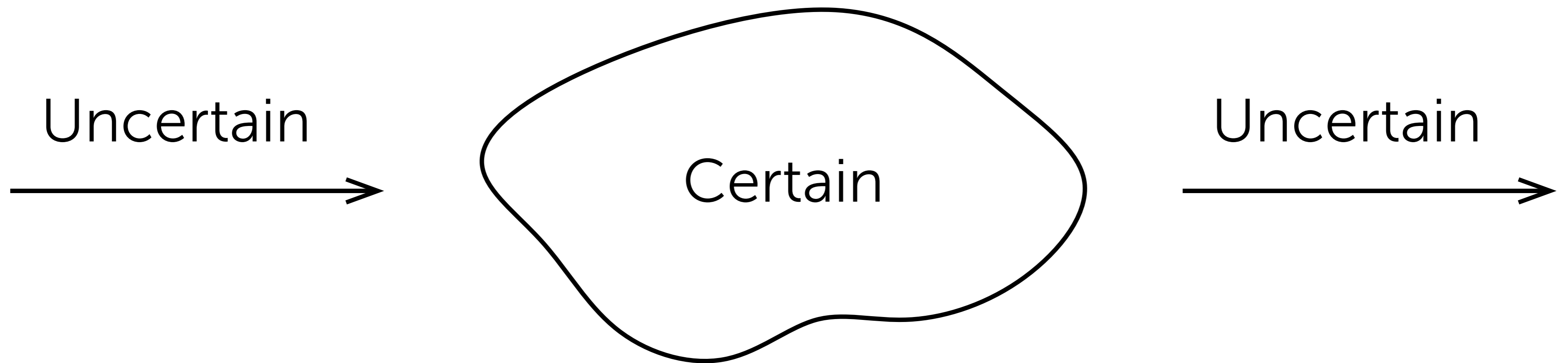
- * Dynamic steady-state temperature
- * Stochastic-temperature reliability
- * Design-space exploration

Uncertainty Quantification

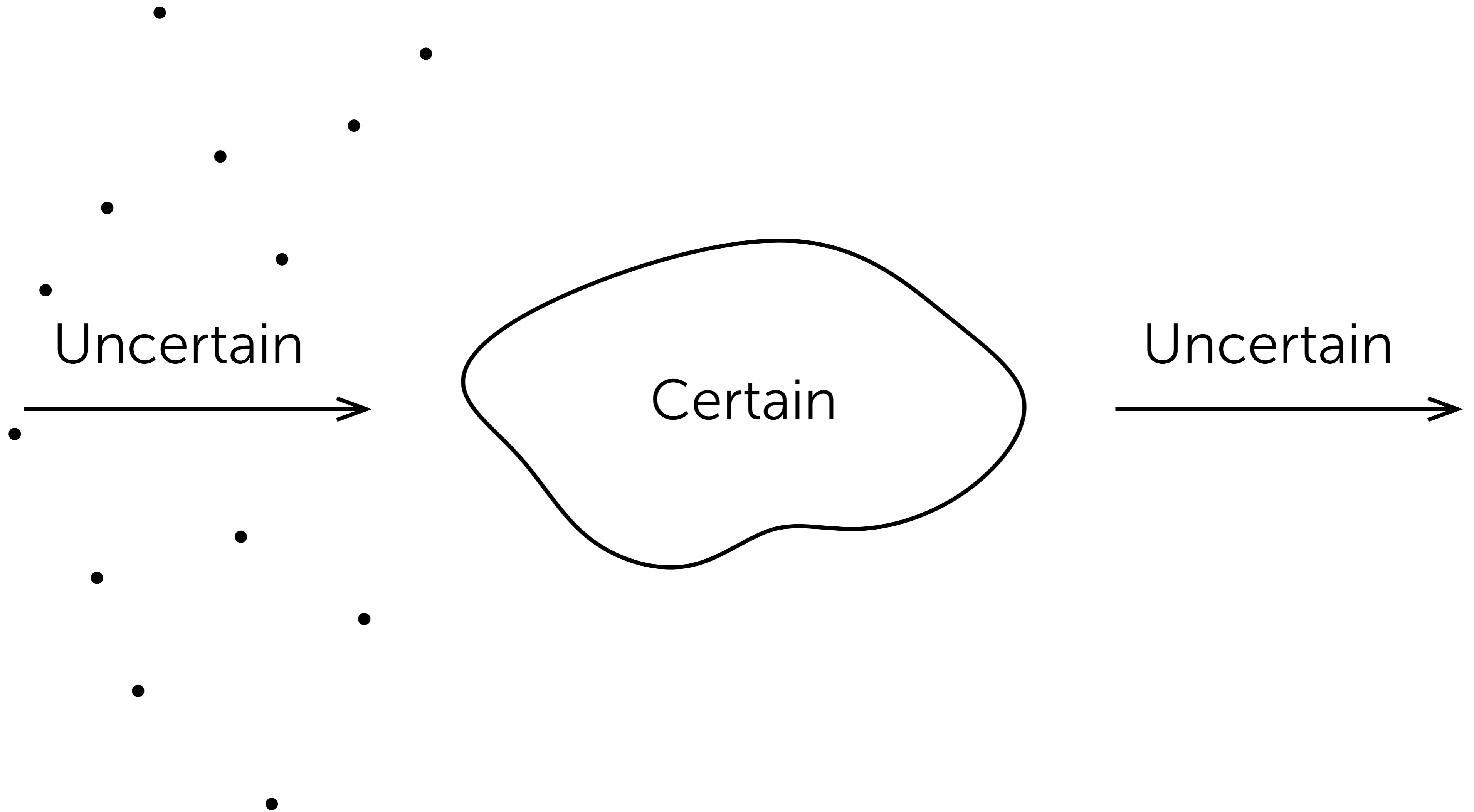


* Designed by Sergiu Rafiliu.

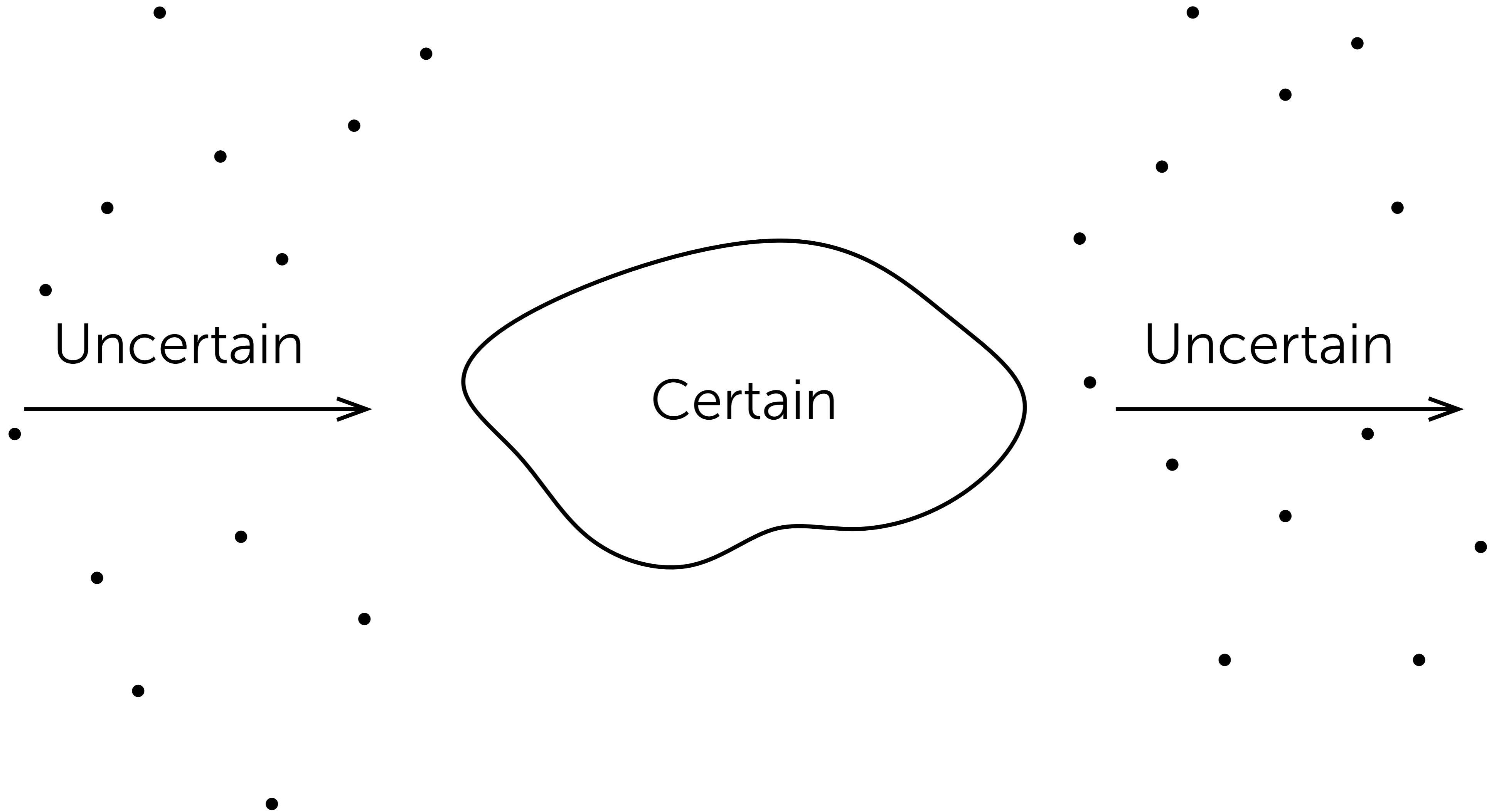
Uncertainty Quantification



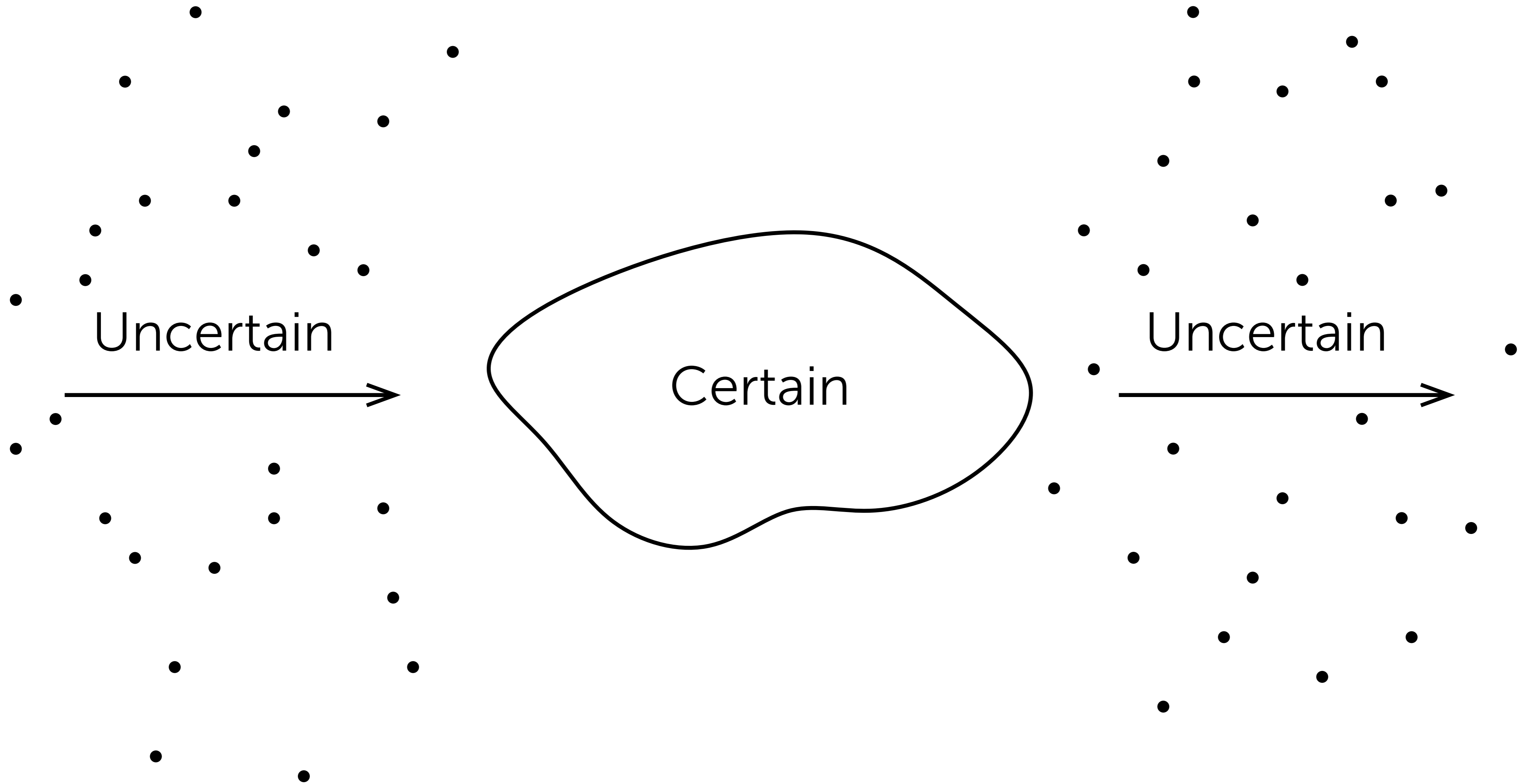
Uncertainty Quantification



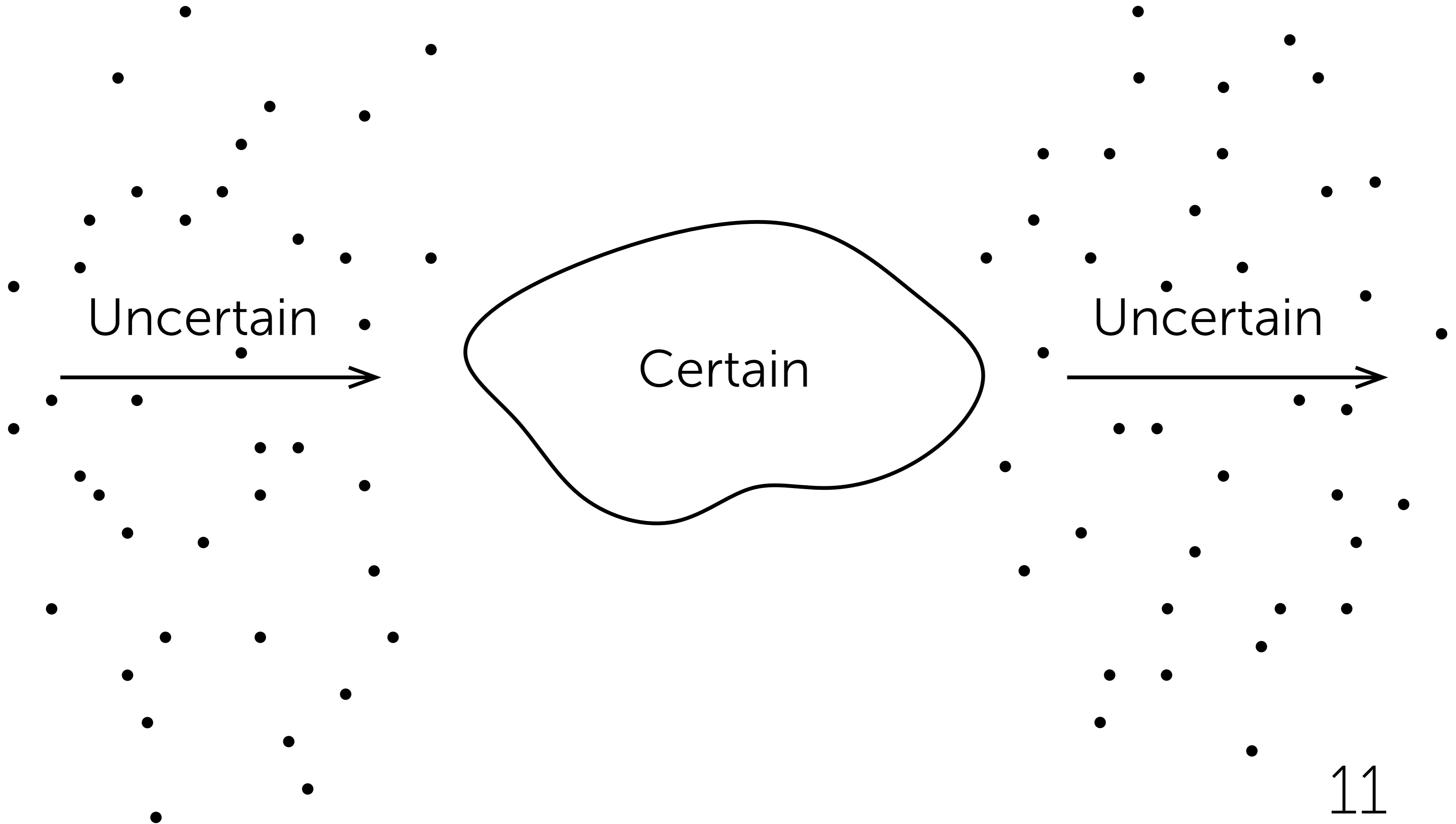
Uncertainty Quantification



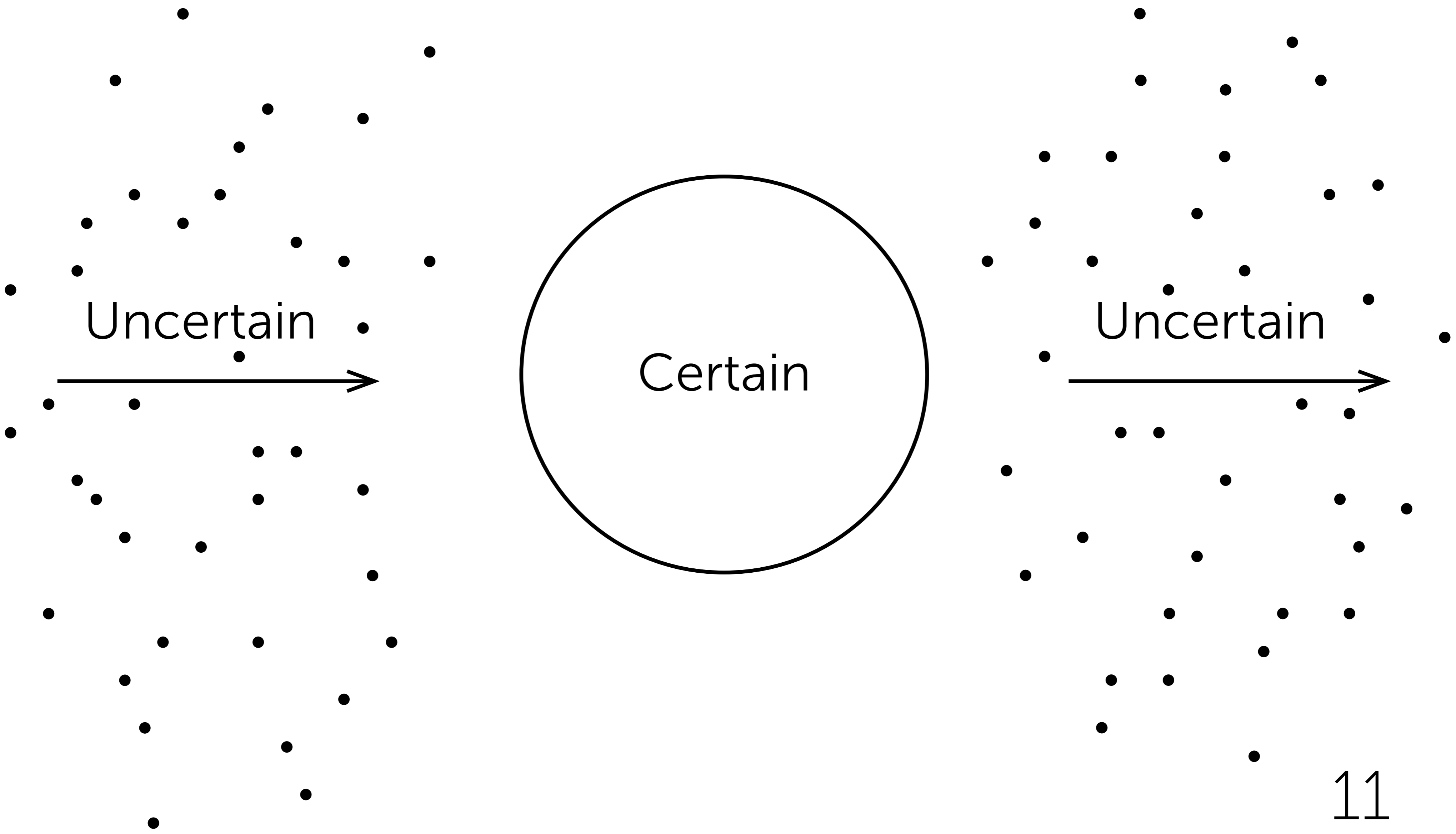
Uncertainty Quantification



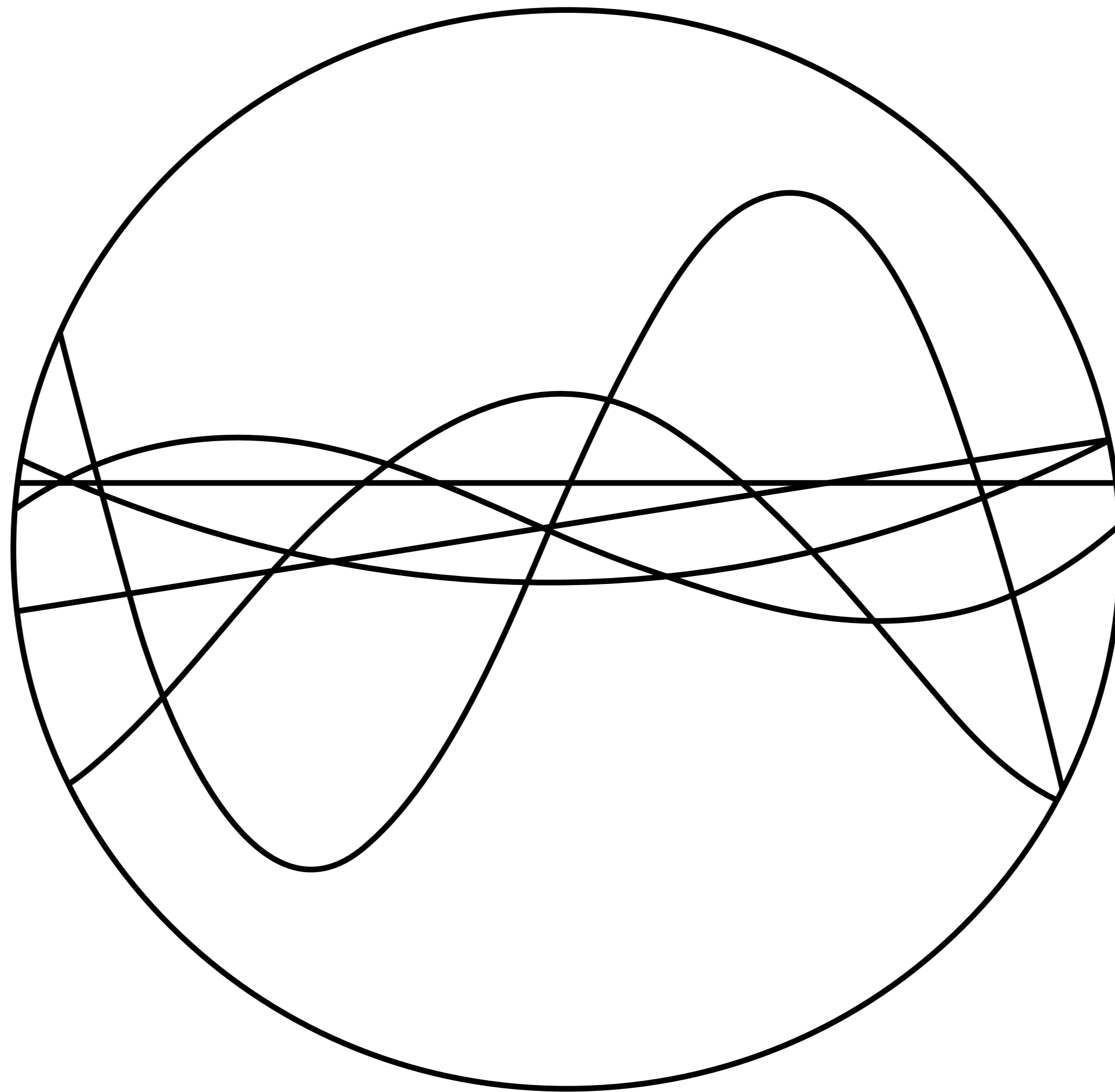
Uncertainty Quantification



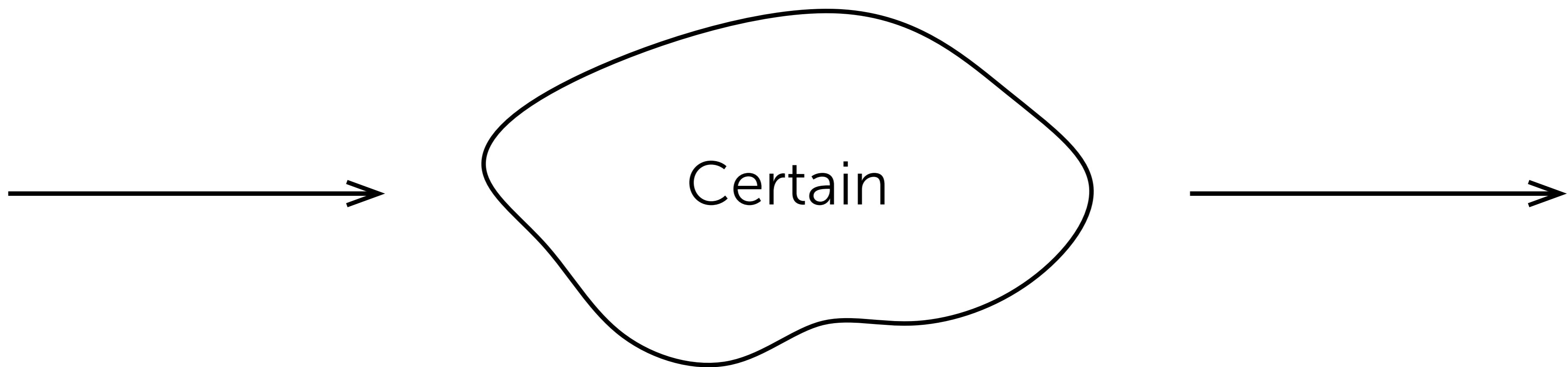
Uncertainty Quantification



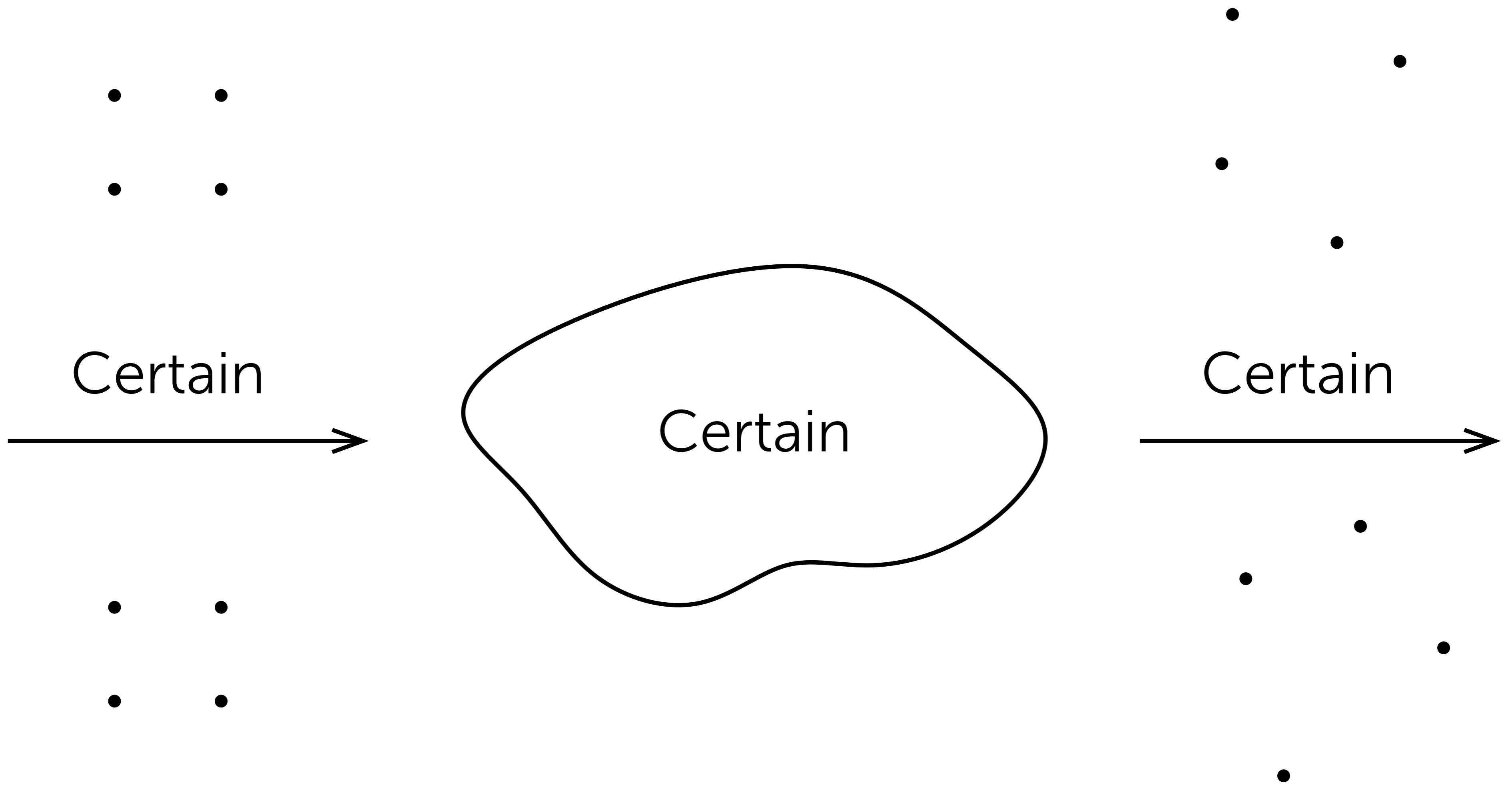
Polynomial Chaos



Polynomial Chaos

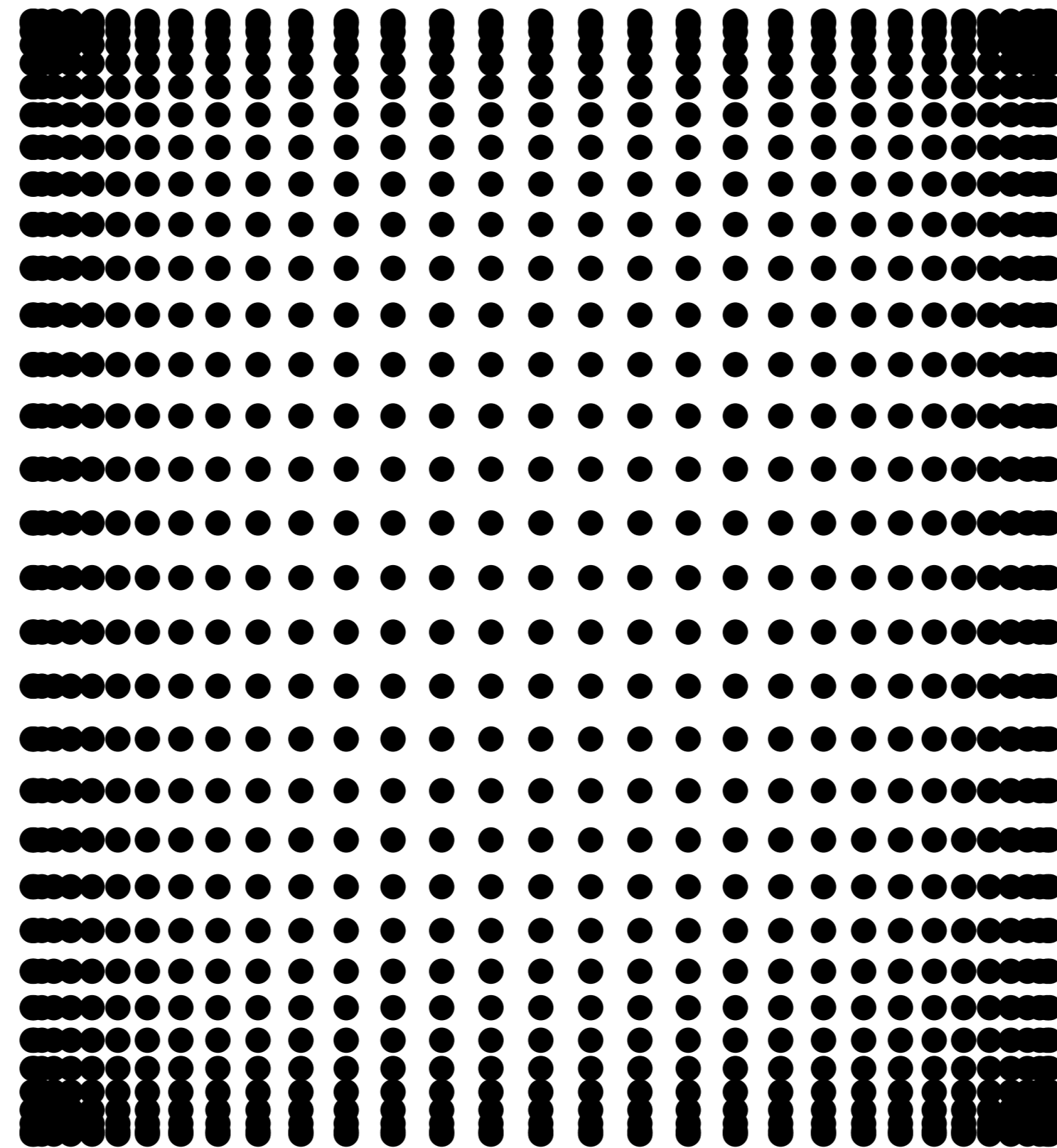


Polynomial Chaos



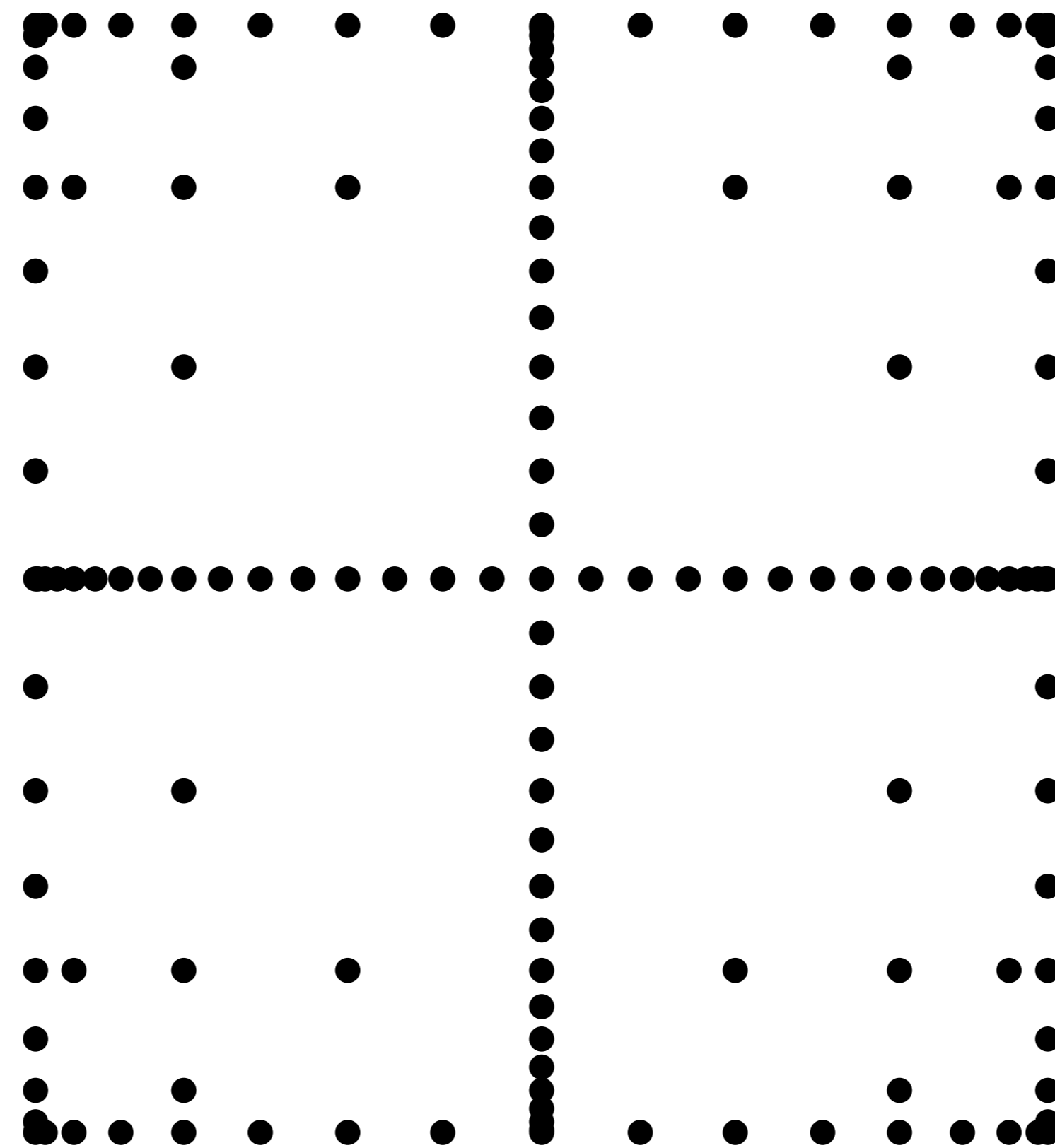
Quadratures

- * Full-tensor-product



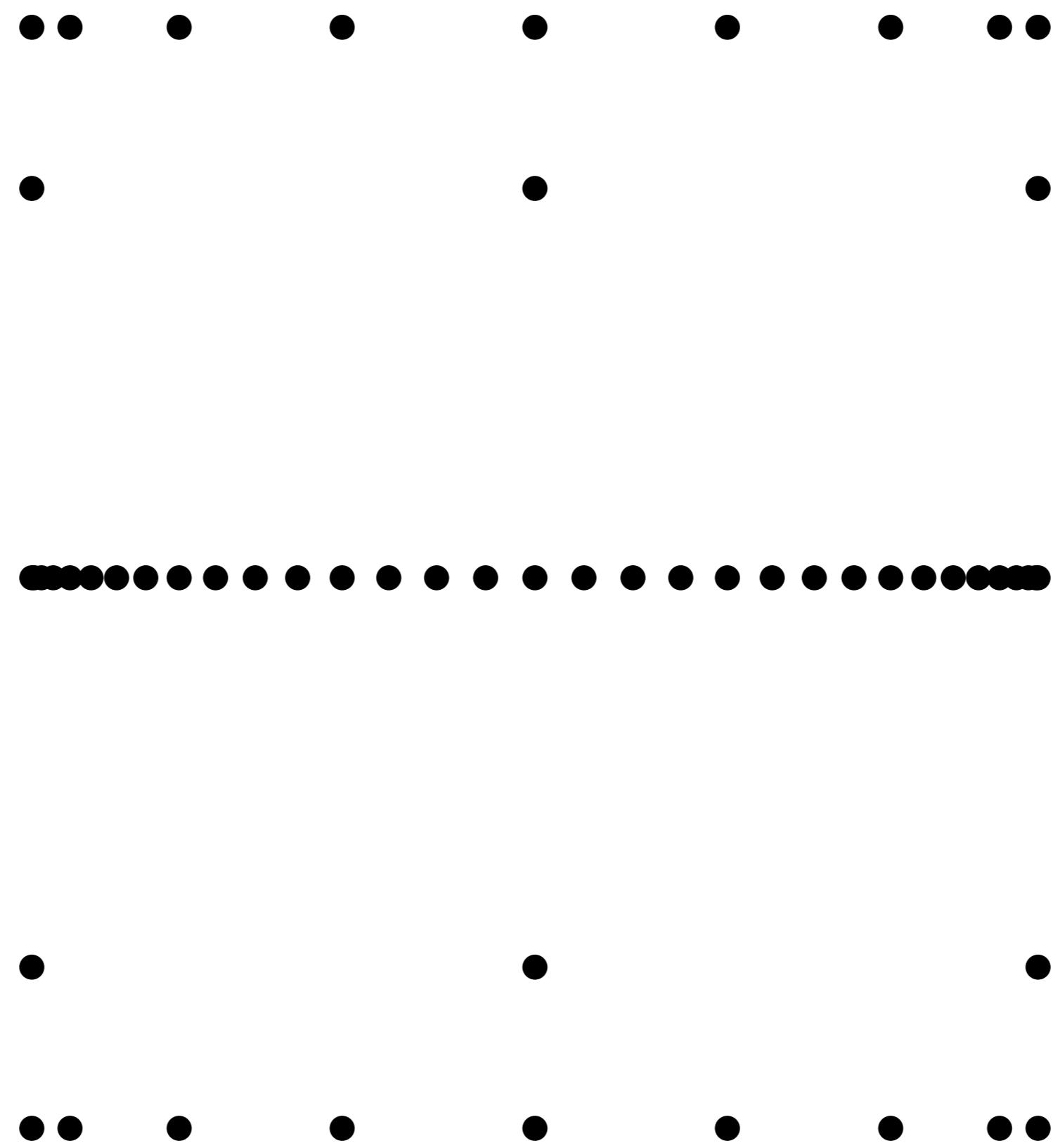
Quadratures

* Isotropic sparse

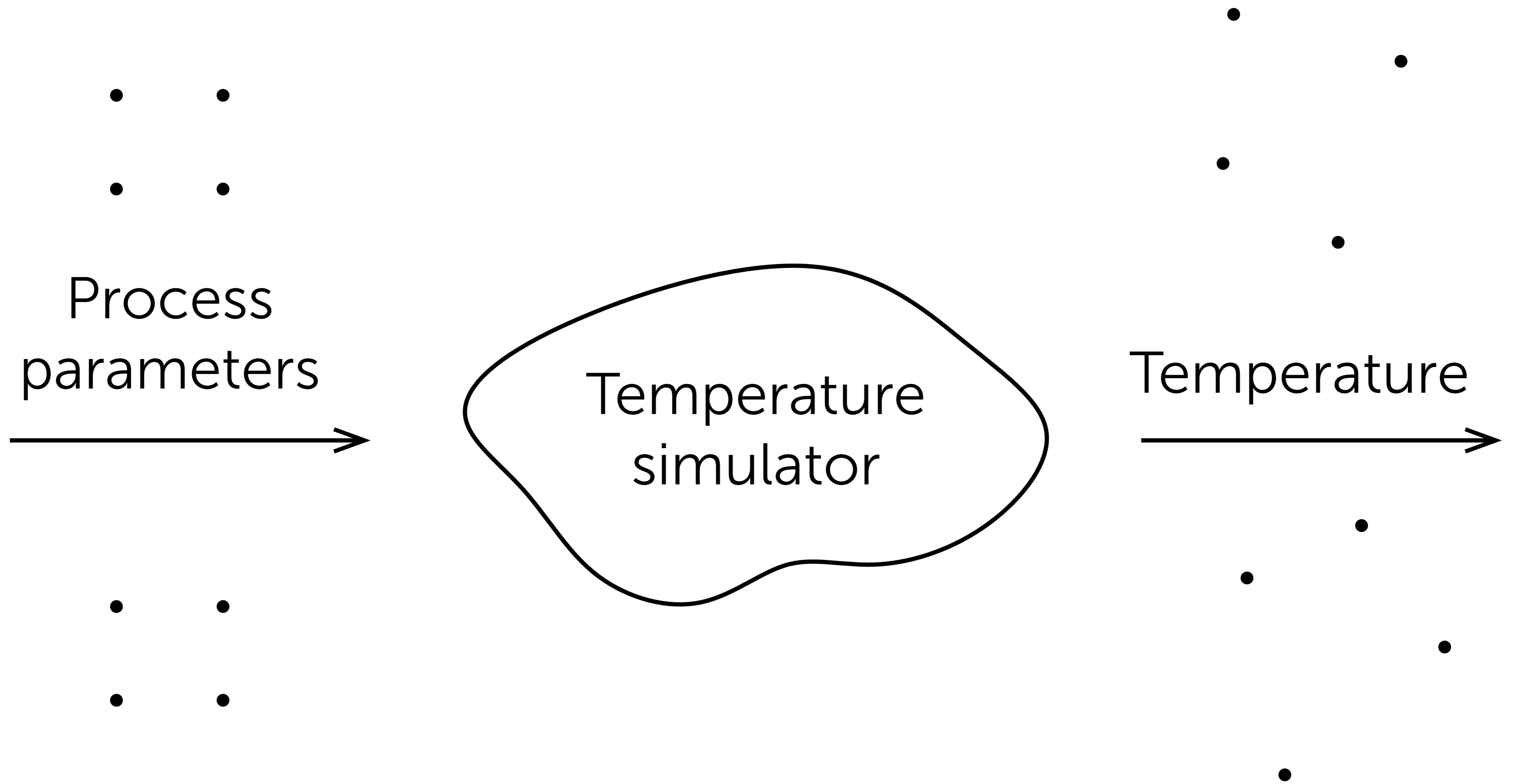


Quadratures

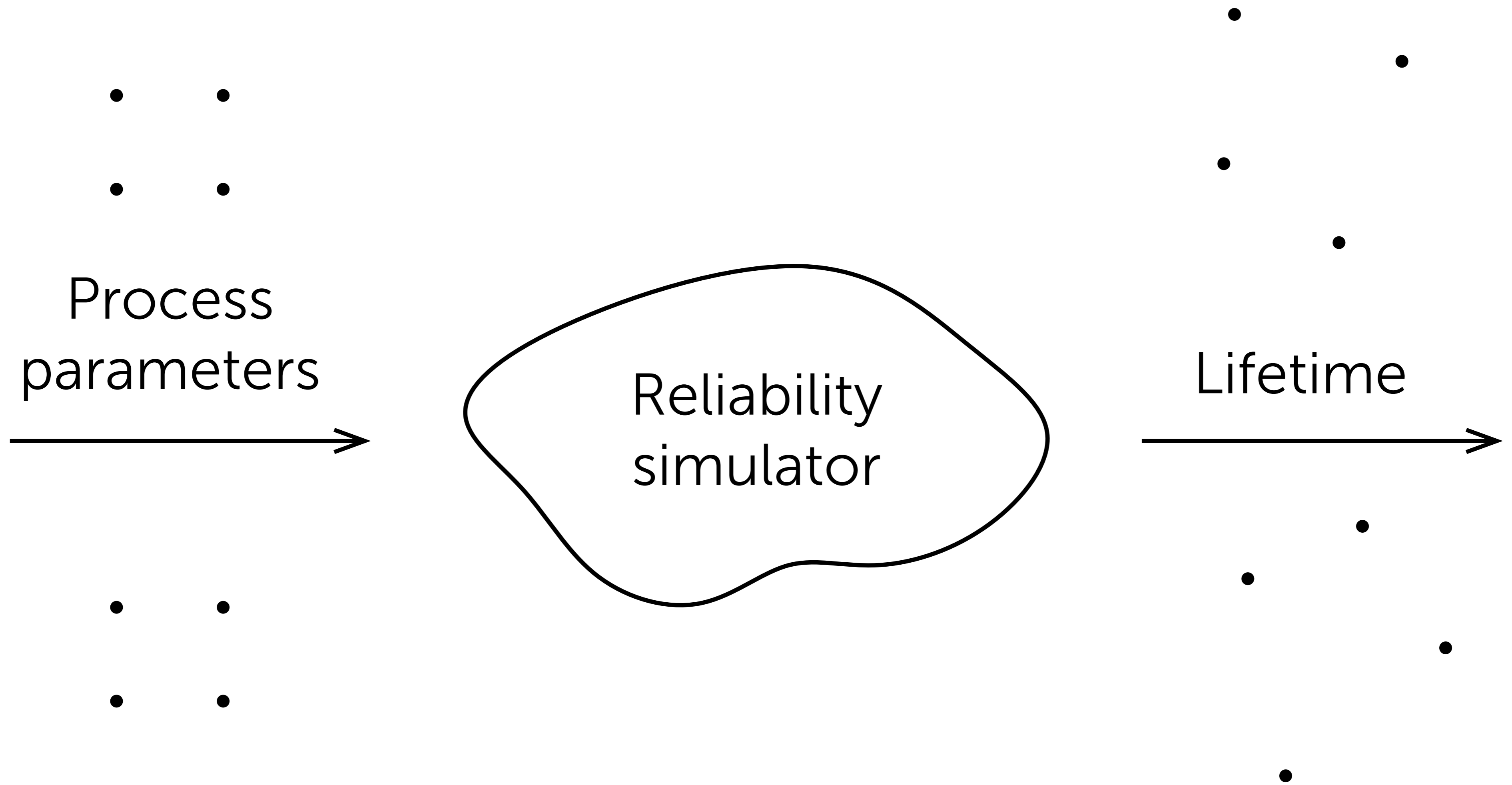
* Anisotropic sparse



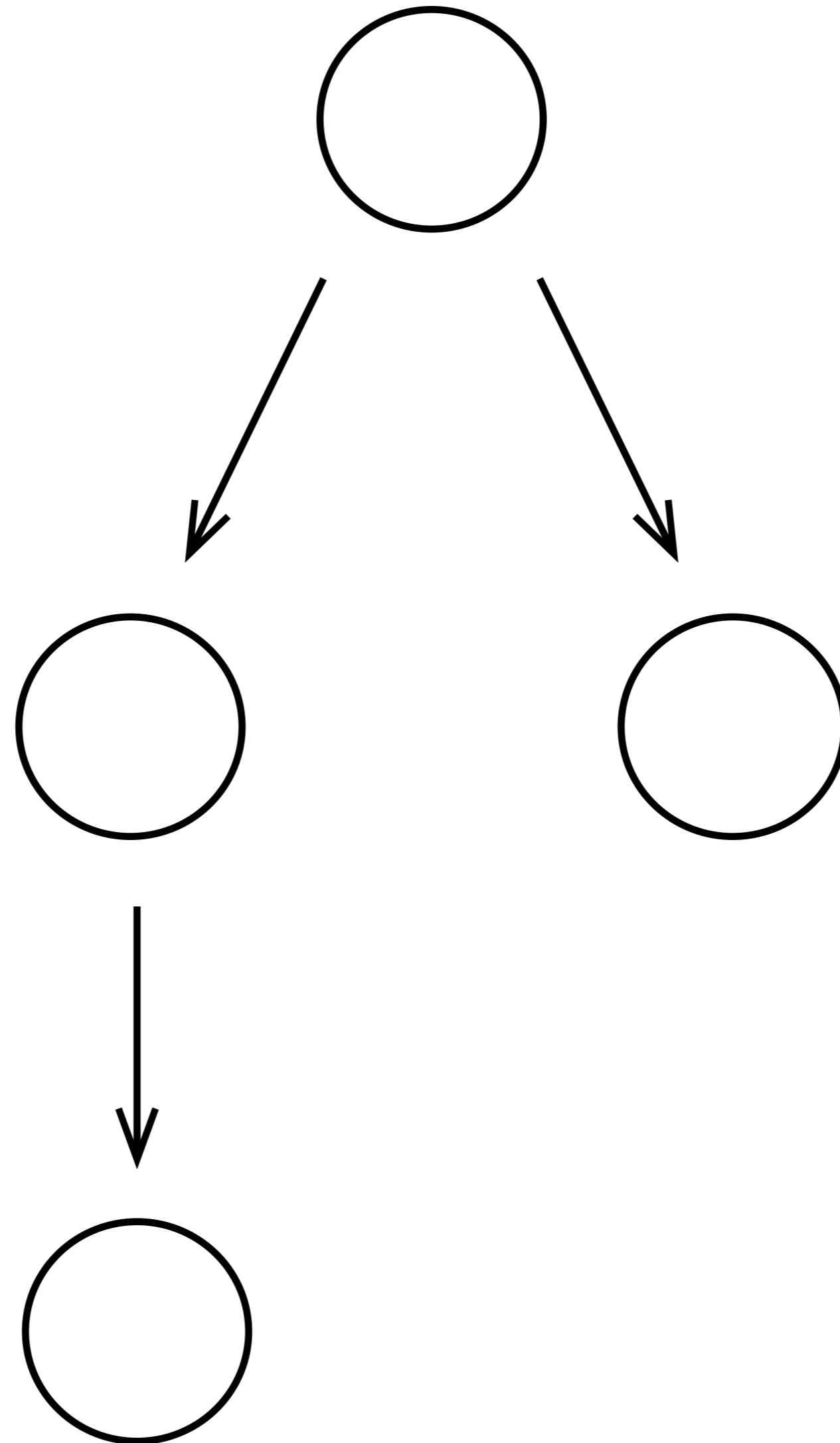
Temperature Analysis



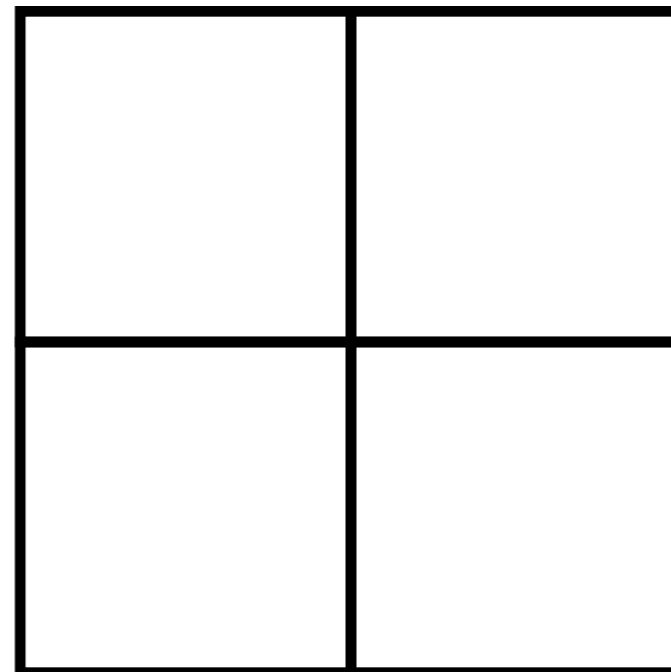
Reliability Analysis



Application



Platform



Core

Uncertain parameters:

- * Effective channel length
- * Gate-oxide thickness

Failure mechanism:

- * Thermal cycling

Optimization

Minimize:

- * Energy

Such that:

- * Deadline

- * Temperature

- * Lifetime

Optimization

Minimize:

- * $\text{Pr}(\text{Energy})$

Such that:

- * Deadline

- * $\text{Pr}(\text{Temperature})$

- * $\text{Pr}(\text{Lifetime})$

Setup

- * 2, 4, 8, 16, and 32 cores
- * 40, 80, 160, 320, and 640 tasks
- * 10 test cases per pair cores/tasks

Calibration

Cores	Vars	Nodes
2	4	57
4	6	69
8	8	81
16	10	93
32	10	101

Optimization

Cores	P, min	D, min	F, %
2	1	1	40
4	5	2	60
8	17	4	70
16	56	8	100
32	300	9	100

Thank you!

Questions?